



www.fciconnect.com		surface	tolerance std	projection	MM
		ASME Y14.5	ASME Y14.5		Scale
		TOLERANCES UNLESS OTHERWISE SPECIFIED			1:1
Dr	T. HOUTZ	2005-03-29	ANGULAR	0.X	A2
Eng	ANDREW TONG	2010-05-11	LINEAR	0.XX	ECN
Chr	C.H. TAN	2010-05-11	0"	0.XXX	Spec ref
Appr	JOEY NG	2010-05-11	Product family	2mm High Power	GS-12-220
R/A RECEPTACLE POWER ASSEMBLY (2 x 2)		Rev.	10052620		C
catalog no		CUSTOMER		sheet 1 of 2	

PDM: Rev:C STATUS:Released Printed: Dec 01, 2010

TOP LAYER DESCRIPTION	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER (DIM"A")
TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	--	--	--	0.65 - 0.80
IMMERSTON TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	0.9 - 1.5um	--	0.70 - 0.80
IMMERSTON SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	0.15 - 0.65um	0.70 - 0.80
COPPER (SEE NOTE 11)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	--	0.70 - 0.80
GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.003 - 0.007	FLASH UP TO 0.0002	--	--	0.69 - 0.80

NOTES:

1. CONNECTOR MATERIALS:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK
UL 94V-0 COMPLIANT
CONTACT: HIGH PERFORMANCE COPPER ALLOY
2. a) CONTACT PLATING (LEAD FREE):
PRESS-FIT TAIL: 0.5um MIN MATTE TIN OVER NICKEL.
SEPARABLE INTERFACE: 0.76um MIN GOLD OVER NICKEL.
b) CONTACT PLATING (LEADED):
PRESS-FIT TAIL: 0.5um MIN TIN-LEAD OVER NICKEL.
SEPARABLE INTERFACE: 0.76um MIN GOLD OVER NICKEL.
3. PRODUCT SPECIFICATION: GS-12-220
4. APPLICATION SPECIFICATION: GS-20-023
5. PRODUCT MARKING (PRODUCT NUMBER & DATE CODE) ON HOUSING IN AREA SHOWN.
6. MINIMUM NOMINAL PCB THICKNESS: 1.6mm
7. REFER TO CUSTOMER DRAWING 10035911 FOR INFORMATION REGARDING PCB LAYOUT OF POWER AND GUIDE MODULES RELATIVE TO SIGNAL MODULES.
8. PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN FCI SPECIFICATION GS-22-008.
9. PACKAGING MEETS FCI SPECIFICATION GS-14-920.
10. HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
11. COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.

RECOMMENDED PCB LAYOUT
COMPONENT SIDE
NOTE 6
SCALE 4:1

FCI	R/A RECEPTACLE POWER ASSEMBLY (2 x 2) <small>catalog no</small>	<small>REV</small> 10052620	<small>Rev.</small> C <small>CUSTOMER</small> sheet 2 of 2
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